

Description

The DFS900HF12I4C1 is a Half Bridge SiC MOSFET Power Module. It integrates high performance SiC MOSFET chips designed for the applications such as Motor drives and Renewable energy.



Features

- Blocking voltage 1200V
- $R_{DS(on)} = 3.0m\Omega$
- Low thermal resistance with Si_3N_4 AMB
- 175°C maximum junction temperature
- Thermistor inside
- Low Switching Losses

Applications

- xEV Applications
- Motor Drives
- Vehicle Fast Chargers
- Smart-Grid/Grid-Tied Distributed Generation

Circuit diagram

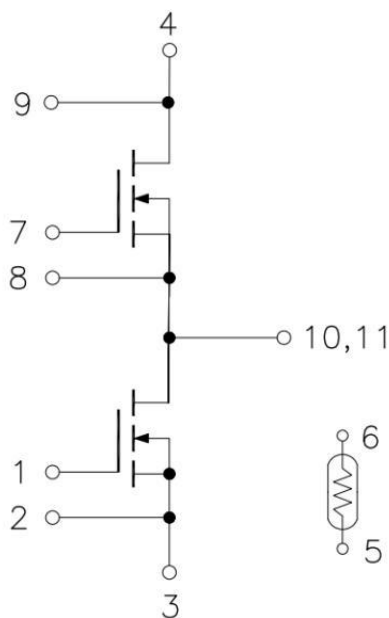


Figure 1. Out drawing & circuit diagram for DFS900HF12I4C1

Pin Configuration and Marking Information

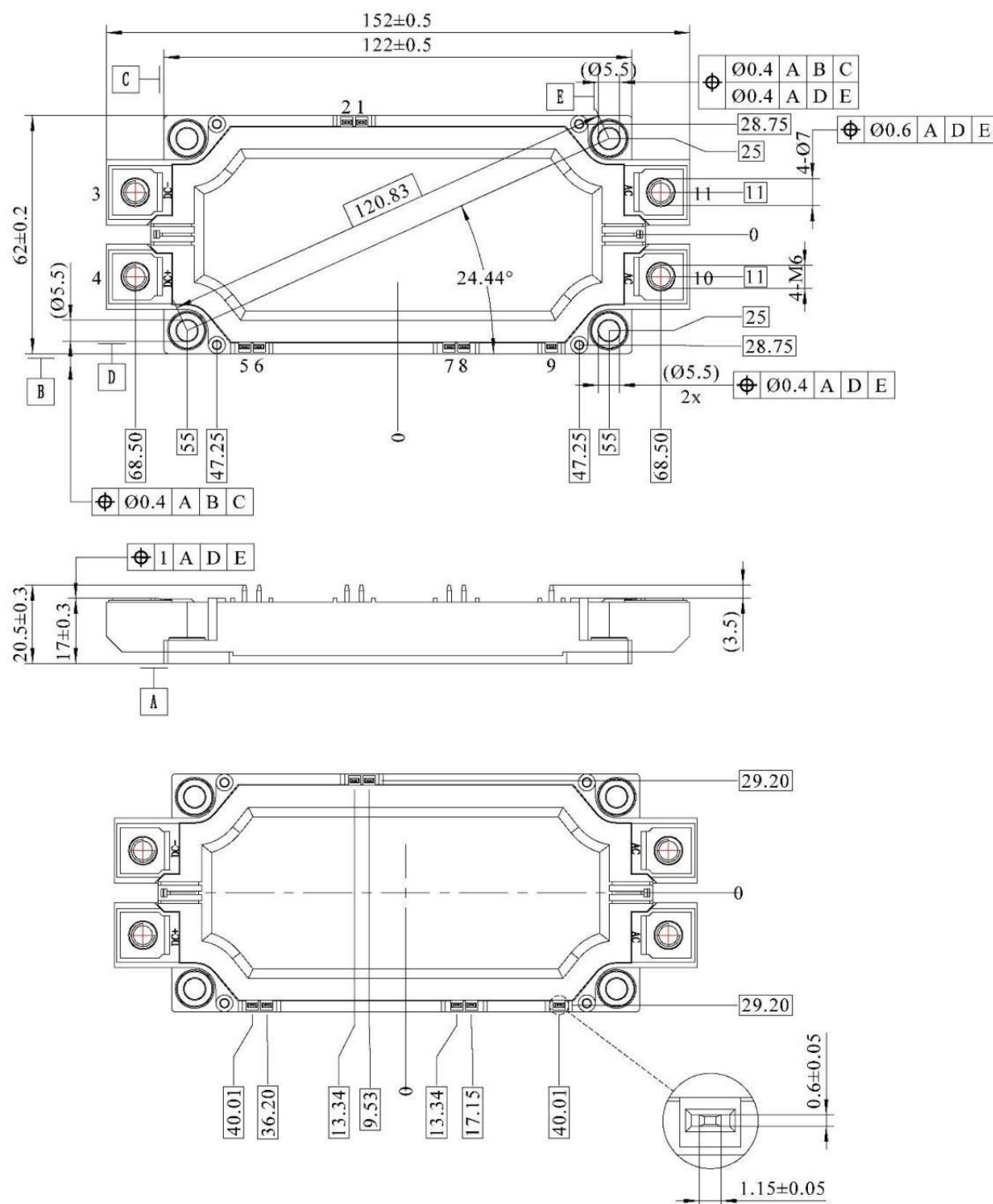


Figure 2. Pin configuration

Module

Parameter	Condition	Value	Unit
Isolation Voltage	RMS, f =50Hz, t =1min	3.4	kV
Material of module baseplate	-	Cu	-
Creepage distance	terminal to heatsink terminal to terminal	14.5 13	mm
Clearance	terminal to heatsink terminal to terminal	12.5 10	mm
CTI	-	>400	-
Module lead resistance, terminals–chip	T _C =25°C	0.5	mΩ
Mounting torque for module mounting	M5, M6	3 to 6	Nm
Weight	-	340	g

Maximum Ratings (T_j =25°C unless otherwise specified)

Symbol	Parameter	Condition	Ratings	Unit
V _{DSS}	Drain-Source Voltage	G-S Short	1200	V
V _{GSS}	Gate-Source Voltage	D-S Short, AC frequency ≥1Hz, Note1	-10 to 22	V
I _{DS}	DC Continuous Drain Current	T _C =25°C, V _{GS} =18V	1000	A
I _{DS}	DC Continuous Drain Current	T _C =60°C, V _{GS} =18V	900	A
I _{SD}	Source (Body diode) Current	T _C =25°C, with ON signal	1000	A
I _{SD}	Source (Body diode) Current	T _C =60°C, with ON signal	900	A
I _{DSM}	Pulse Forward Current	T _C =25°C, Pulse width =1ms, V _{GS} =20V, Note2	1800	A
P _{tot}	Total Power Dissipation	T _C =25°C	3000	W
T _{jmax}	Max Junction Temperature	-	175	°C
T _{stg}	Storage Temperature	-	-40 to 125	°C

Note1: Recommended Operating Value, +18V/-5V, +18V/-4V, +15V/-4V

Note2: Pulse width limited by maximum junction temperature

NTC characteristics

Symbol	Parameter	Condition	Value			Unit
			Min.	Typ.	Max.	
R ₂₅	Resistance	T _C =25°C	-	5	-	kΩ
ΔR/R	Deviation of R ₁₀₀	T _C =100°C, R ₁₀₀ =493Ω	-5	-	5	%
P ₂₅	Power dissipation	T _C =25°C	-	-	20	mW
B _{25/50}	B-value	$R_2 = R_{25} \exp [B_{25/50}(1/T_2 - 1/(298,15 \text{ K}))]$	-	3375	-	K
B _{25/80}	B-value	$R_2 = R_{25} \exp [B_{25/80}(1/T_2 - 1/(298,15 \text{ K}))]$	-	3411	-	K
B _{25/100}	B-value	$R_2 = R_{25} \exp [B_{25/100}(1/T_2 - 1/(298,15 \text{ K}))]$	-	3433	-	K

MOSFET Electrical characteristics (T_j=25°C unless otherwise specified, chip)

Symbol	Item	Condition		Value			Unit
				Min.	Typ.	Max	
V _{(BR)DSS}	Drain-Source Breakdown Voltage	V _{GS} =0V, I _D =900μA		1200	-	-	V
I _{DSS}	Zero gate voltage drain Current	V _{DS} =1200V, V _{GS} =0V	T _j =25°C	-	1.17	200	μA
			T _j =150°C		36.97	200	
V _{GS(th)}	Gate-source threshold Voltage	I _D =315mA V _{DS} =V _{GS}	T _j =25°C	1.8	2.89	3.6	V
			T _j =150°C	1.5	2.1	3.6	
I _{GSS}	Gate-Source Leakage Current	V _{GS} =20V, V _{DS} =0V	T _j =25°C	-	2.35	900	nA
			T _j =150°C	-	145.7	900	
R _{DS(on)}	Static drain-source On-state resistance	I _D =900A V _{GS} =+15V	T _j =25°C	-	3.0	3.3	mΩ
			T _j =150°C	-	3.93	4.3	
V _{DS(on)}	Static drain-source On-state Voltage	I _D =900A V _{GS} =+15V	T _j =25°C	-	2.73	-	V
			T _j =150°C	-	3.46	-	
C _{iss}	Input Capacitance	V _D =1000V, V _{GS} =0V f =200kHz, V _{AC} =25mV		-	52.2	-	nF
C _{oss}	Output Capacitance			-	1.60	-	
C _{rss}	Reverse transfer Capacitance			-	0.13	-	
R _{Gint}	Internal gate resistor	-		-	0.7	-	Ω
Q _G	Total gate charge	V _{DD} =800V, I _D =540A, V _{GS} =+18/- 4V		-	1890	-	nC
t _{d(on)}	Turn-on delay time	V _{DD} =600V I _D =900A V _{GS} =+18/-4V R _g =5.1Ω Inductive load switching operation	T _j =25°C	-	0.223	-	μs
			T _j =150°C	-	0.193	-	
t _r	Rise time		T _j =25°C	-	0.162	-	μs
			T _j =150°C	-	0.132	-	
t _{d(off)}	Turn-off delay time		T _j =25°C	-	0.441	-	μs
			T _j =150°C	-	0.549	-	
t _f	Fall time		T _j =25°C	-	0.11	-	μs
			T _j =150°C	-	0.136	-	
E _{on}	Turn-on power dissipation		T _j =25°C	-	76.39	-	mJ
			T _j =150°C	-	62.52	-	

E _{off}	Turn-off power dissipation		T _j =25°C	-	70.99	-	mJ
			T _j =150°C	-	73.49	-	
R _{th(j-c)}	FET Thermal Resistance	Junction to Case		-	0.05	-	K/W
R _{th(c-f)}	Contact thermal Resistance	With thermal conductive grease, Note3		-	0.015	-	K/W

Note3: Assumes Thermal Conductivity of grease is 0.9W/m · K and thickness is 50um.

Body Diode Electrical characteristics ($T_j=25^\circ\text{C}$ unless otherwise specified, chip)

Symbol	Item	Condition		Value			Unit
				Min.	Typ.	Max	
V_{SD}	Body Diode Forward Voltage	$V_{GS} = -5\text{V}$ $I_{SD} = 900\text{A}$	$T_j = 25^\circ\text{C}$	5.0	5.53	7.0	V
			$T_j = 175^\circ\text{C}$	4.0	5.04	6.0	
T_{rr}	Reverse recovery time	$V_{DD} = 600\text{V}$ $I_D = 900\text{A}$ $V_{GS} = +18/-4\text{V}$	$T_j = 25^\circ\text{C}$	-	0.048	-	μs
			$T_j = 150^\circ\text{C}$	-	0.66	-	
Q_{rr}	Reverse recovery charge	$R_g = 5.1\Omega$ Inductive load switching operation	$T_j = 25^\circ\text{C}$	-	3.64	-	μC
			$T_j = 150^\circ\text{C}$	-	8.35	-	
E_{rr}	Diode switching power dissipation	switching operation	$T_j = 25^\circ\text{C}$	-	0.42	-	mJ
			$T_j = 150^\circ\text{C}$	-	1.11	-	

Test Conditions

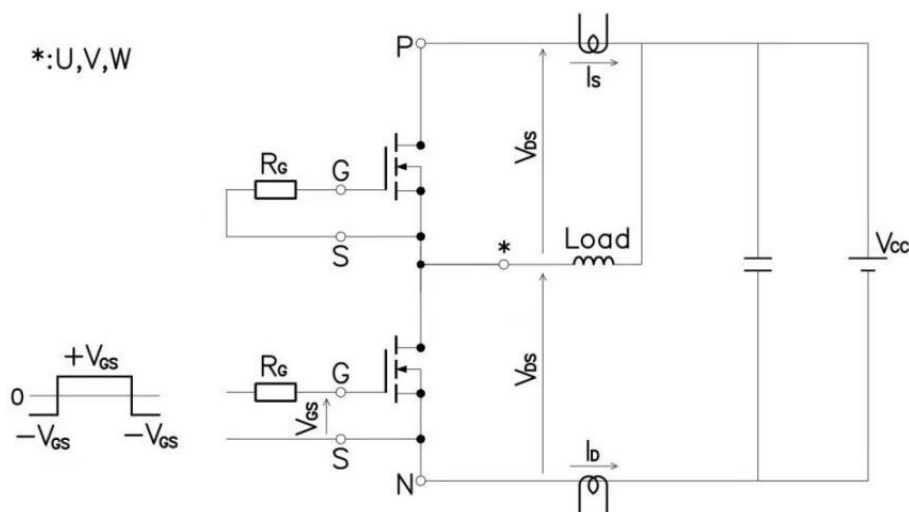


Figure 3. Switching time measure circuit

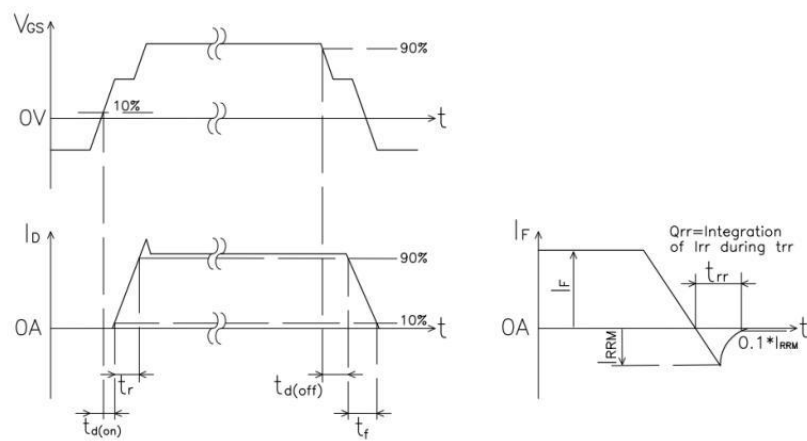


Figure 4. Switching time definition

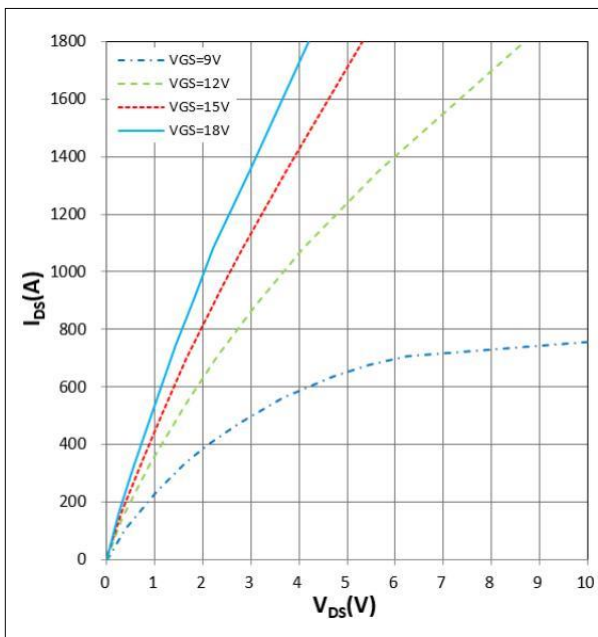


Figure 5. I_{DS} vs V_{DS}

$T_j = 25^\circ\text{C}$

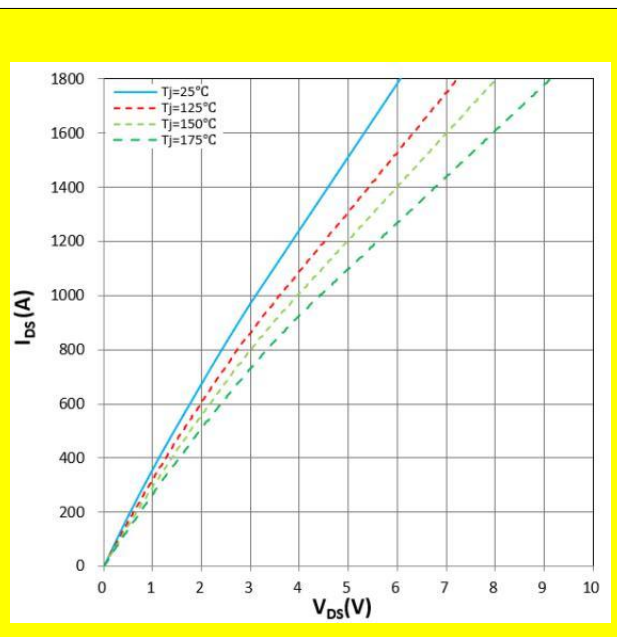


Figure 6. I_{DS} vs V_{DS}

$V_{GS} = 15\text{V}$

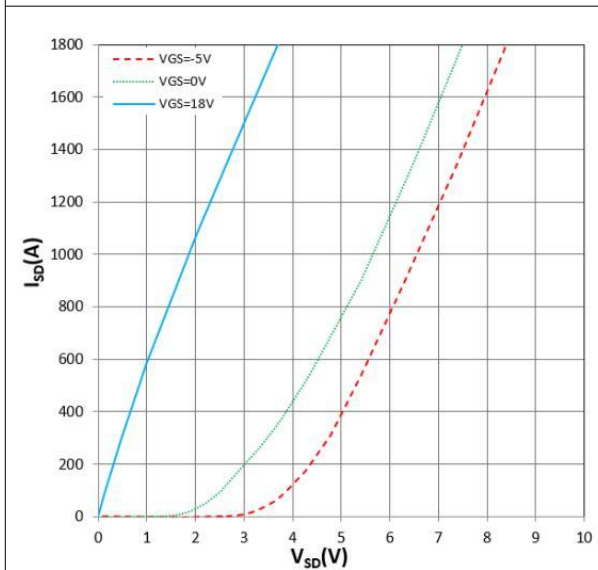


Figure 7. I_{SD} vs V_{SD}

$T_j = 25^\circ\text{C}$

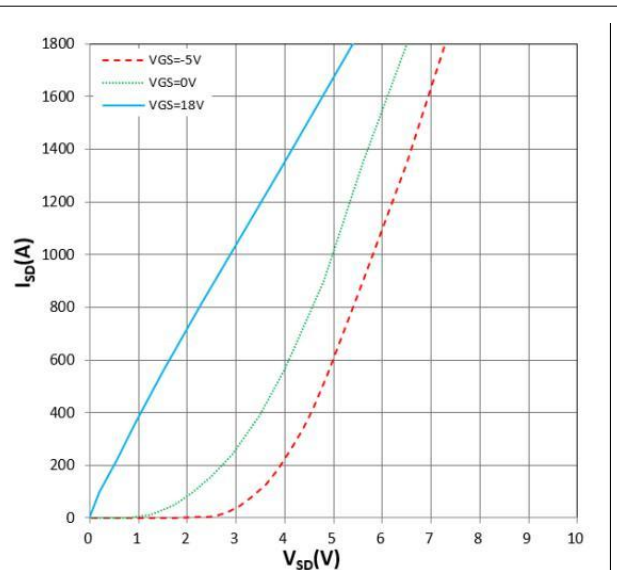


Figure 8. I_{SD} vs V_{SD}

$T_j = 175^\circ\text{C}$

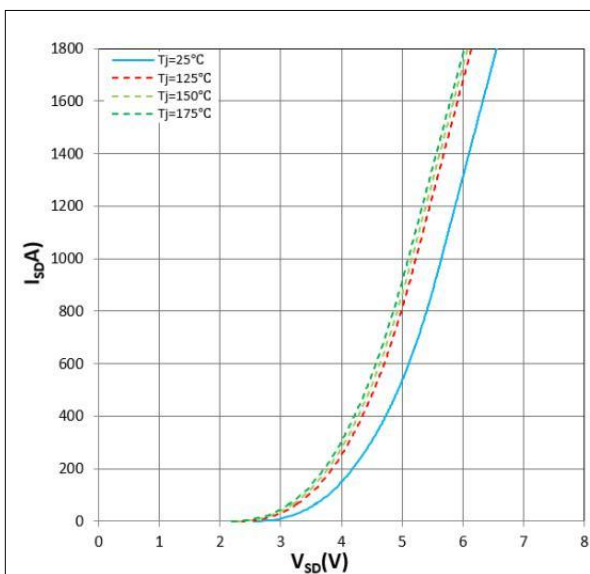


Figure 9. I_{SD} vs V_{SD}
 $V_{GS} = -5V$

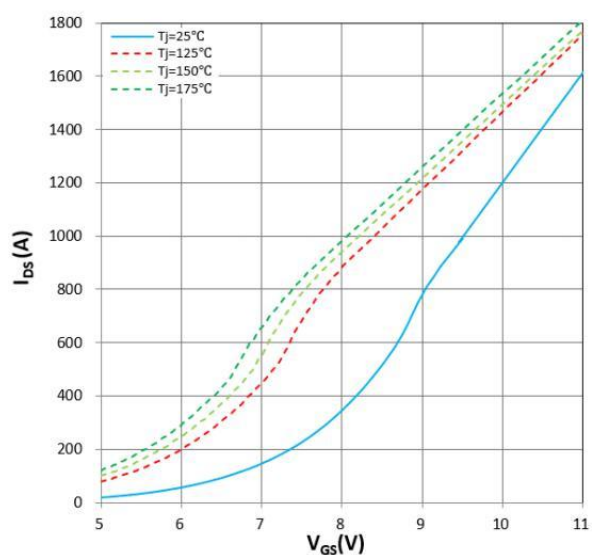


Figure 10. I_{DS} vs V_{GS}
 $V_{DS} = 20V$

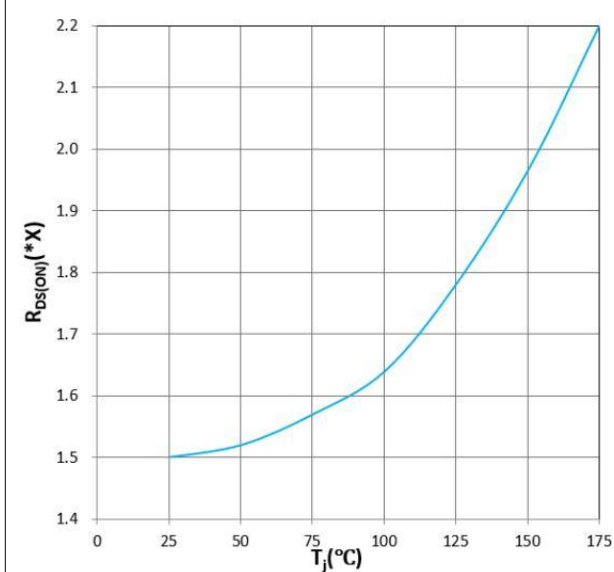


Figure 11. $R_{DS(on)}$ vs T_J
 $V_{GS} = +15V$, $I_D = 900A$, $1.0X = 2.0m\Omega$

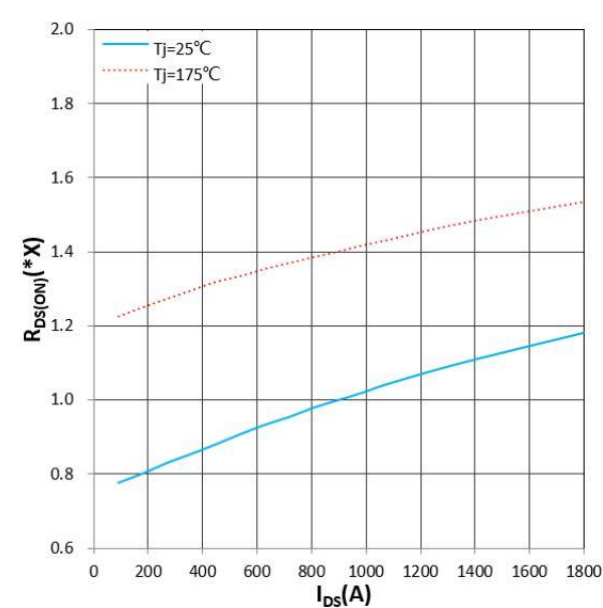


Figure 12. $R_{DS(on)}$ vs I_{DS}
 $T_J = 25^\circ C / 175^\circ C$, $V_{GS} = +15V$, $1.0X = 2.0m\Omega$

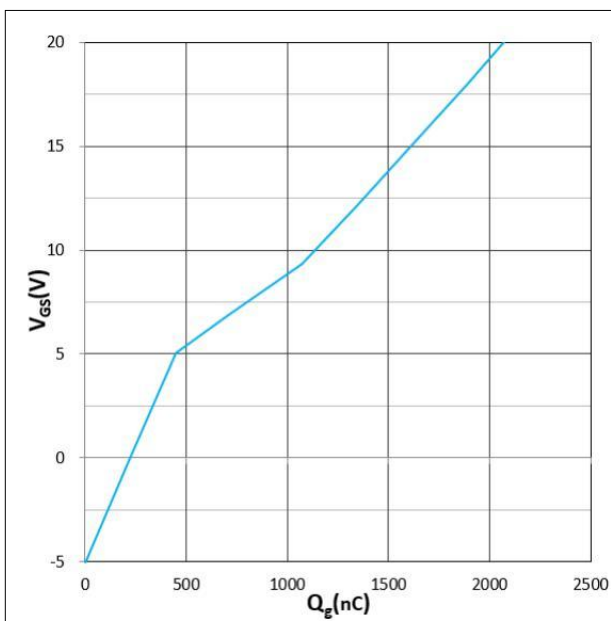


Figure 13. V_{GS} vs Q_g

$T_j = 25^\circ\text{C}$, $V_{DS} = 800\text{V}$, $I_D = 540\text{A}$

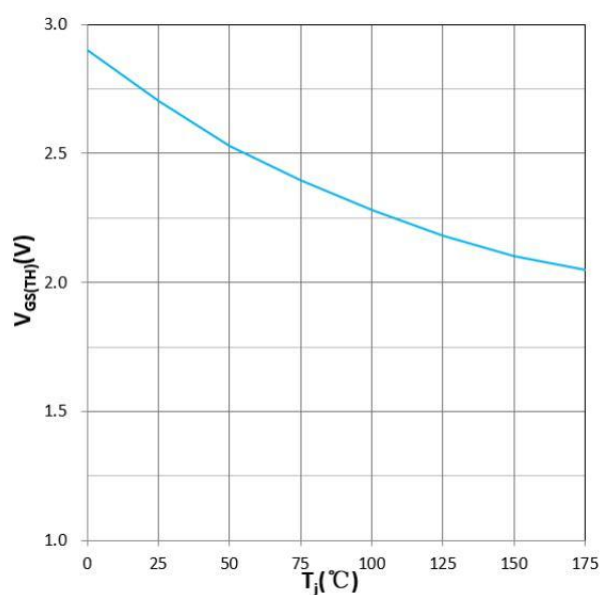


Figure 14. $V_{GS(TH)}$ vs T_j

$V_{GS} = V_{DS}$, $I_D = 315\text{mA}$

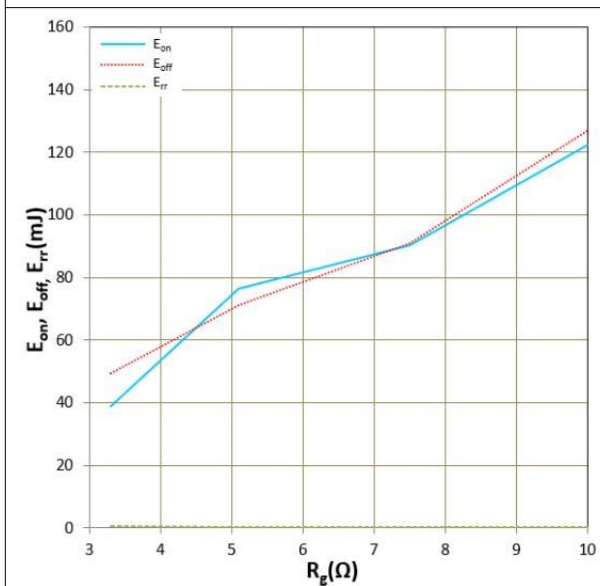


Figure 15. E_{on} , E_{off} , E_{rr} vs R_g

$T_j = 25^\circ\text{C}$, $V_{DD} = 600\text{V}$, $V_{GS} = +18\text{V}/-4\text{V}$, $I_D = 900\text{A}$
Inductive Load

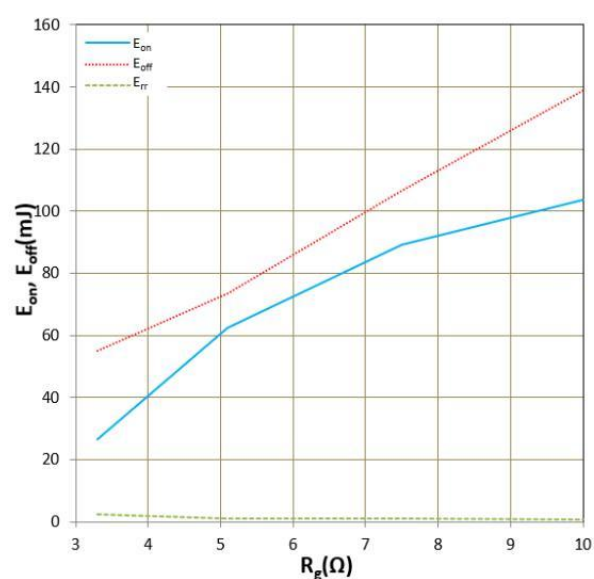


Figure 16. E_{on} , E_{off} , E_{rr} vs R_g

$T_j = 150^\circ\text{C}$, $V_{DD} = 600\text{V}$, $V_{GS} = +18\text{V}/-4\text{V}$, $I_D = 900\text{A}$
Inductive Load

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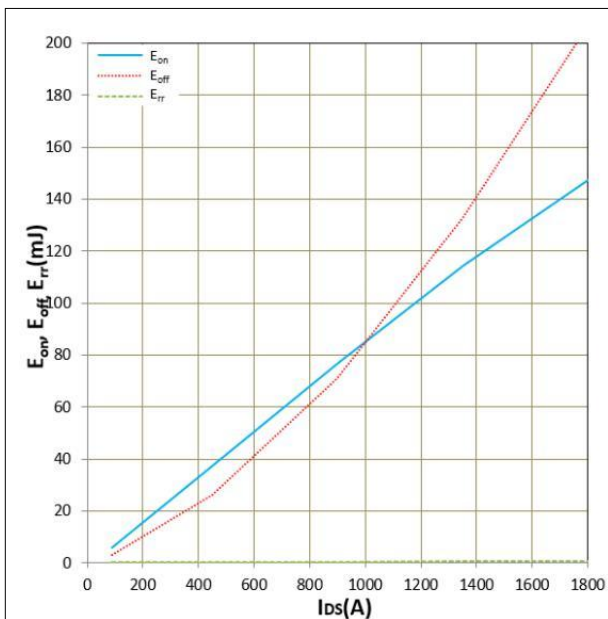


Figure 17. E_{on} , E_{off} , E_{rr} vs I_D
 $T_j = 25^\circ\text{C}$, $V_{DD} = 600\text{V}$, $V_{GS} = +18\text{V}/-4\text{V}$,
 $R_g = 5.1\Omega$, Inductive Load

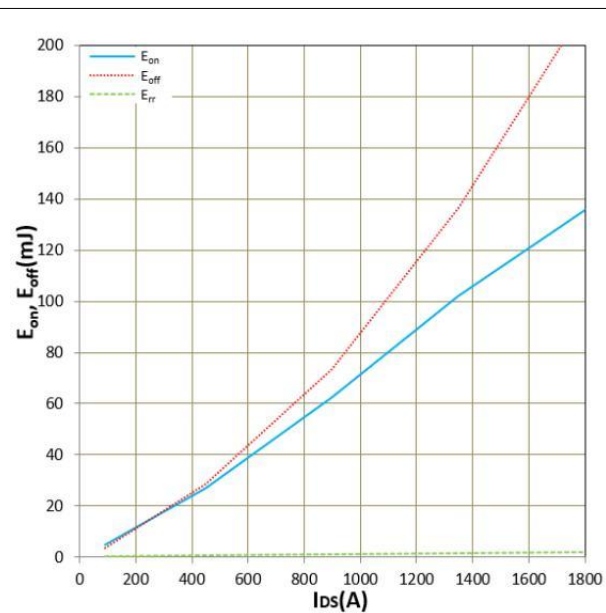


Figure 18. E_{on} , E_{off} , E_{rr} vs I_D
 $T_j = 150^\circ\text{C}$, $V_{DD} = 600\text{V}$, $V_{GS} = +18\text{V}/-4\text{V}$,
 $R_g = 5.1\Omega$, Inductive Load

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